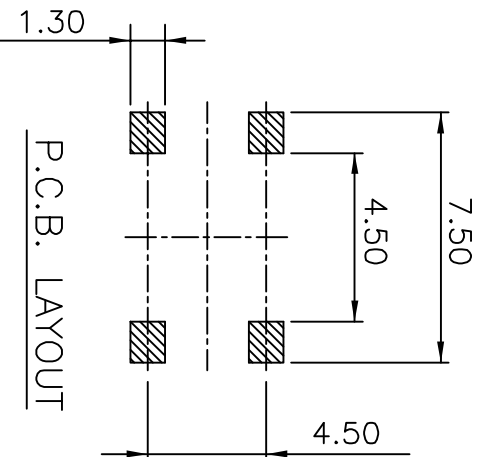
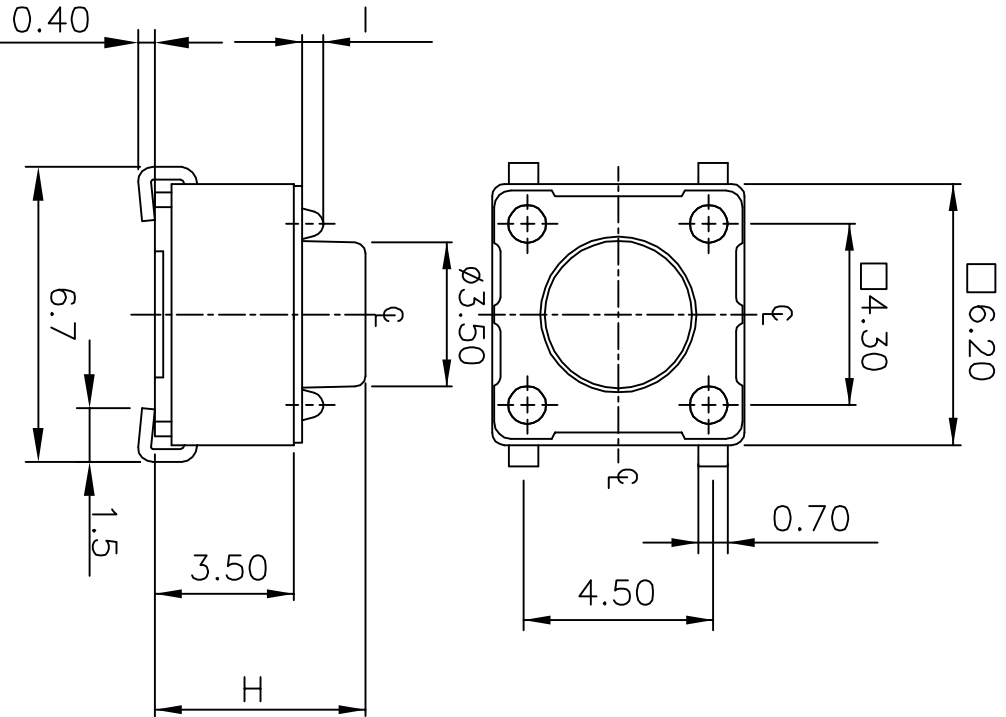
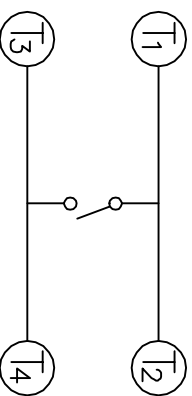


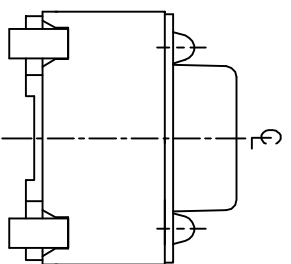
NOTE:
 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. GENERAL TOLERANCES MAX.±0.20mm.



P.C.B. LAYOUT



CIRCUIT DIAGRAM



DTSJ-62以上□-V	0.6 MAX
DTSJ-61□-V	0.5 MAX
PROD. NO.	1

DTSJ-66□-V	13.0
DTSJ-65□-V	9.5
DTSJ-64□-V	7.3(SQ)
DTSJ-63□-V	7.0
DTSJ-62□-V	5.0
DTSJ-61□-V	4.3
PROD. NO.	H

△	A	DWG.REL	DATE	APPD.
	ZONE	REV	DESCRIPTION	

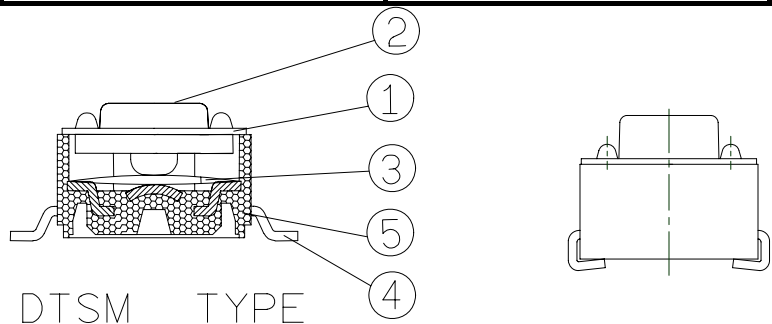
APPD:	QTY:
CHKD:	SCALE: 8 : 1
DR: JUAN	REV: A
DESIGN:	UNITS: mm

園達實業股份有限公司 DPTRONICS MANUFACTURING INC.	PART NO: DTSJ-6__-V	MATL: FINISH:
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PART NAME:	6X6 TACTILE SWITCH SMT TYPE
DWG NO:	R D 5 P 6 J-V

ITEM	DESC.	Q'TY	MATERIALS	TREATMENT	REMARK
1.	COVER	1	STAINLESS STEEL	NONE	-
2.	STEM	1	HIGH – TEMP THERMOPLASTIC NYLON UL 94V-0	→	-
3.	CONTACT	1	STAINLESS STEEL	WITH SILVER CLADDING	-
4.	TERMINAL	1	BRASS	WITH SILVER PLATING	-
5.	BASE	1	HIGH – TEMP THERMOPLASTIC NYLON UL 94V-0	MOLDERD BROWN	-

Remark :



DTSM TYPE

① Prod. No. : DTS □ - 6 □ □ □ - □ - V - □

M=Surface Mounting Type

J= Surface Mounting Type

Dimension H:

1 = 4.3 mm

2 = 5.0 mm

3 = 7.0 mm

44(48)= 7.3 mm

5 = 9.5 mm

6 = 13 mm

Package Style:

B = Tube

△T/R = Tape & Reel

<△M=Except DTSM-66>

<△J=Only DTSJ-61.62>

Soldering:

V=Lead Free

□=With Silver Plating 0.5uM

Color Of Stem For Operating Force:

K = Black ,100g

N = Brown ,160g

R = Red ,260g

S = Salmon,320g

Y = Yeelow,520g

B	新增 DTSJ-61.62	邱明義
A	DWG.REL	邱明義
REV.	ECO. NO.	APPD.

TITLE: TACTILE SWITCH SMT/NON-WASHABLE TYPE		APPD. : 邱明義
PRROD NO.:DTS□-6□□□-□-V-□		CHKD. : 林后謀
FILE NO.: E-V-CT04		PR. : 楊佩儒
REV : B	SHEET:1 of 1	



1. Style

This specification describes “TACTILE SWITCH”, mainly used as signal switch of electric devices, with the general requirements of mechanical and electrical characteristic.

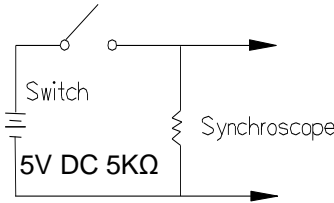
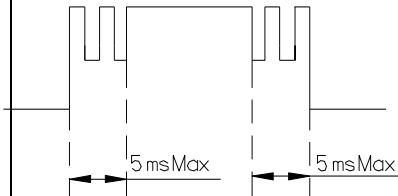
1.1 Operating Temperature Range: -25°C+70°C

1.2 Storage Temperature Range : -30°C+80°C


2. Current Range: 50mA, 12 VDC

3.Type of Actuation: Tactile feedback

4.Test Sequence:

	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
APPEARANCE	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
ELECTRIC PERFORMANCE	2	Contact Resistance	Applying a static load 1.5~2 times the operating force to the center made with a 1 kHz small current contact resistance meter.	100mΩ Max.
	3	Insulation Resistance	Measurements shall be made following application of 500 V DC potential across terminals and cover for 1 minute ±5 seconds.	100MΩ Min.
	4	Dielectric Withstanding Voltage	250 V AC(50Hz or 60Hz) shall be applied across terminals and cover for 1 minute	There shall be no breakdown or flashover.
	5.	Bounce	3 to 4 operations at a rate of 1 cycles per second 	5 m seconds Max. 



MECHANICAL PERFORMANCE	6.	Operating Force	Applied in the direction of operation. 	OF					
				U	K	N	R	S	Y
				70±30 [60N±29N]	100±50 [90N±49N]	160±50 [150N±49N]	260±50 [250N±49N]	320±80 [310N±79N]	520±130 [500N±127N]
	7.	Stroke	Placing the switch such that the direction of switch operation is vertical and then gradually increasing the load applied to the stem, the stroke distance for the stem to come to a stop shall be measured.	0.25 +0.2/-0.1 mm					
	8.	Stop Strength	Placing the switch such that the direction of switch operation is vertical, a static load of 3 kgf(29.4N) shall be applied in the direction of stem operation for a period of 15 seconds	1.As shown in item 4~7 2.Contact Resistance: 200mΩ Max 3.Insulation Resistance: 10MΩ Min					
9.	Solder Heat Resistance	(Through Hole Type (Soldering Temperature:260 ±5°C (Duration of Solder Immersion: 5 ± 1 seconds. (Frequency of Soldering Process 2 times max. (PCB is 1.6 mm in thickness) ■SMT Type ~DTSM Series(4/4)	1.Shall be free from pronounced backlash and falling-off or breakage terminals 2.As shown in item 4、5 3.Contact Resistance: 200mΩ Max 4.Insulation Resistance:10MΩ Min						
10.	Vibration	Shall be vibrated in accordance with Method 201A of MIL-STD-202F 1.Frequency: 10-55-10Hz in 1-min/cycle. 2.Direction: 3 vertical directions including the directions of operation 3.Test time: 2 hours each direction. 4.Swing distance=1.5mm	1.As shown in item 4~7 2.Contact Resistance: 200mΩ Max 3.Insulation Resistance: 10MΩ Min						



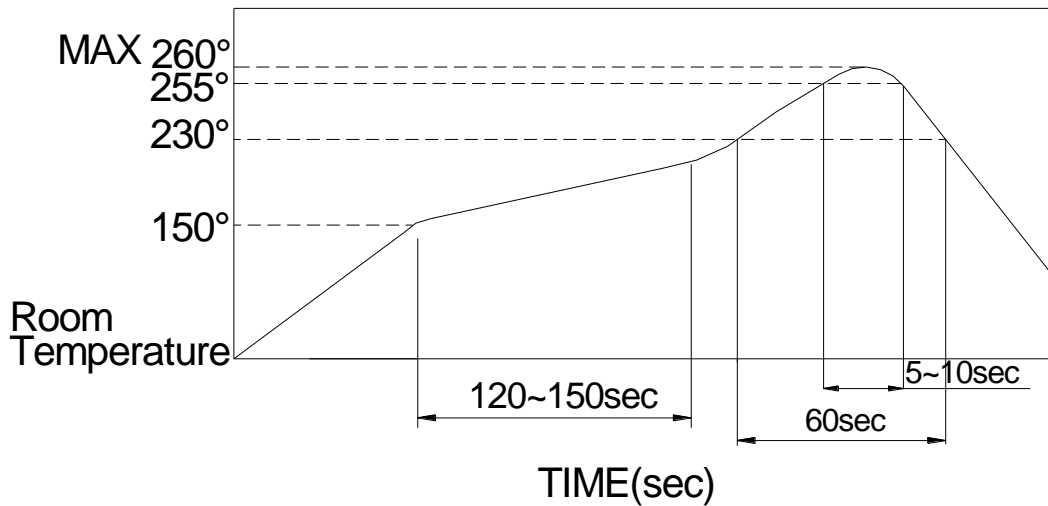
MECHANICAL PERFORMANCE	11	Shock	Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F 1)Acceleration; 50G 2)Action time:11±1m seconds 3)Testing Direction: 6 sides 4)Test Cycle: 3 times in each direction	1)As shown in item 4~7 2)Contact Resistance: 200mΩ Max 3)Insulation Resistance: 10MΩ Min
	12	Solder ability	Through Hole Soldering 1)Temperature : 245±3°C Lead-Free solder : M705E JIS Z 3282 A (Tin 96.5% , Silver 3% , Copper 0.5%) 2)Flux : 5~10 sec 3)Duration of solder Immersion : 5±1 sec	No anti-soldering and the coverage of dipping into solder must more than 66% was requested.
DURABILITY	13	Operating Life	Measurements shall be made following the test forth below: 1)5 mA,5 VDC resistive load 2)Applying a static load the operating force to the center of the stem in the direction of operation 3)Cycle of Operation: (Through Hole 、 S.M.T Dome=Phosphor Bronze) 200,000 cycle's Min. For 100,160gf 100,000 cycle's Min. For 260gf 50,000 cycle's Min. For 320,520gf (S.M.T Dome=Stainless Steel) 1,000,000 cycle's Min~100,160gf 500,000 cycle's Min~260gf 300,000 cycle's Min~320 、 520gf	1)As shown in item 4 、 5 2)Operating force:±50% of initial force. 3)Contact Resistance: 10Ω Max 4)Insulation Resistance: 10MΩ Min 5)Bounce: 10 m seconds Max
WEATHER-PROOF	14	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: 1)Temperature:-25±3°C 2)Time:96 hours	1)As shown in item 4~7 2)Contact Resistance: 200mΩ Max 3)Insulation Resistance: 10MΩ Min
	15	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: 1)Temperature:80±2°C 2)Time:96 hours	1)As shown in item 4~7 2)Contact Resistance: 200mΩ Max 3)Insulation Resistance: 10MΩ Min



	16	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: 1)Temperature:40±2°C 2)Relative Humidity:90~95% 3)Time:96 hours	1)As shown in item 4~7 2)Contact Resistance: 200mΩ Max 3)Insulation Resistance: 10MΩ Min
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5. SOLDERING CONDITIONS:

■ Condition for Reflow Soldering – S.M.T Series



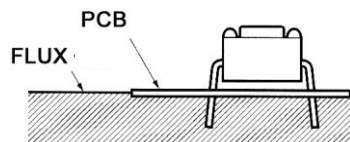
- The condition mentioned above is the temperature on the Cu foil of the PCB surface. There are cases where board's temperature greatly differs from switch's surface be used not to allow switch's surface temperature to exceed 260°C.

■ Manual Soldering

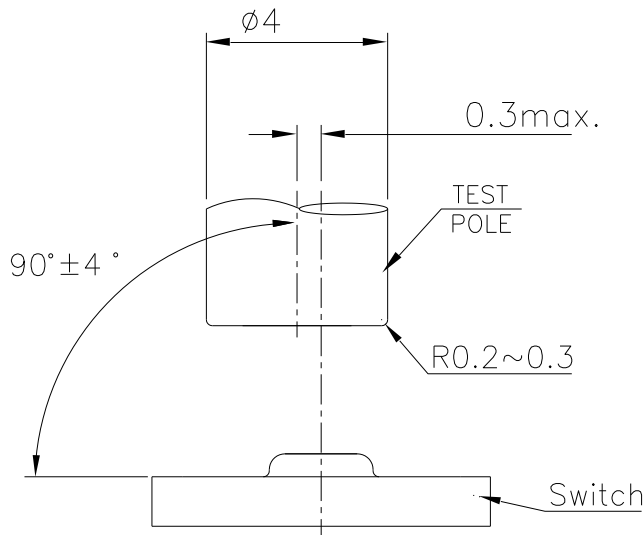
Soldering Temperature	Max.350°C
Continuous Soldering Time	Max. 5 seconds

■ Precautions in Handling

1. Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
2. Except for washable type do not wash the switch body.
3. Please make sure that there is no flux rose over the surface of the PCB



■ Operating Conditions



■ Notes on storage conditions:

Do not store in the following environment or it may affect product's function and solderability:

1. temperature of -10 (max) ~ +40 (min) °C & humidity at 85% (min)
2. environment with corrosive gas
3. storage over 6 months
4. place of direct sunlight

Store with proper packaging conditions and to avoid loading heavy force

We suggest to use the products within 3 months or at least 6 months.

After opening the package, the rest products must be stored in the appropriate moisture-proof & airtight environment.